



Material Content Data Sheet



Sales Product Name		BSC12DN20NS3 G		Issued		2. August 2018		
MA#		MA000862670						
Package		PG-TDSON-8-5		Weight*		124.02 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.374	1.11	1.11	11078	11078
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		91	
	non noble metal	iron	7439-89-6	0.038	0.03		305	
	non noble metal	copper	7440-50-8	37.762	30.45	30.49	304478	304874
	non noble metal	copper	7440-50-8	0.071	0.06	0.06	569	569
wire	non noble metal	copper	7440-50-8	0.071	0.06	0.06	569	569
encapsulation	organic material	carbon black	1333-86-4	0.096	0.08		774	
	plastics	epoxy resin	-	6.812	5.49		54923	
	inorganic material	silicondioxide	60676-86-0	41.061	33.11	38.68	331086	386783
leadfinish	non noble metal	tin	7440-31-5	1.452	1.17	1.17	11705	11705
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1335	1335
solder	non noble metal	tin	7440-31-5	0.030	0.02		246	
	noble metal	silver	7440-22-4	0.038	0.03		307	
	non noble metal	lead	7439-92-1	1.455	1.17	1.22	11735	12288
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		27	
	non noble metal	iron	7439-89-6	0.011	0.01		91	
	non noble metal	copper	7440-50-8	11.320	9.13	9.14	91275	91393
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		54	
	non noble metal	iron	7439-89-6	0.022	0.02		180	
	non noble metal	copper	7440-50-8	22.292	17.97	18.00	179741	179975
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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